## CD54AC02, CD74AC02 QUADRUPLE 2-INPUT POSITIVE-NOR GATES

SCHS304C - JANUARY 2001 - REVISED JUNE 2002

- AC Types Feature 1.5-V to 5.5-V Operation and Balanced Noise Immunity at 30% of the Supply Voltage
- Speed of Bipolar F, AS, and S, With Significantly Reduced Power Consumption
- Balanced Propagation Delays
- ±24-mA Output Drive Current
   Fanout to 15 F Devices
- SCR-Latchup-Resistant CMOS Process and Circuit Design
- Exceeds 2-kV ESD Protection Per MIL-STD-883, Method 3015

#### CD54AC02...F PACKAGE CD74AC02...E OR M PACKAGE (TOP VIEW) 14 VCC 1Y 1A [ 13**∏** 4Y 1B 🛮 3 12 4B 2Y 🛮 11 🛮 4A 2A 10 3Y 2B [ 6 9 🛮 3B 8[] 3A GND [] 7

## description

The 'AC02 devices contain four independent 2-input NOR gates that perform the Boolean function  $Y = \overline{A} \cdot \overline{B}$  or  $Y = \overline{A} + \overline{B}$  in positive logic.

#### ORDERING INFORMATION

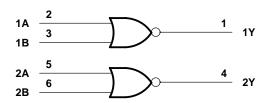
TA	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – E	Tube	CD74AC02E	CD74AC02E
EE°C to 125°C	SOIC - M	Tube	CD74AC02M	AC02M
–55°C to 125°C	SOIC - W	Tape and reel	CD74AC02M96	ACUZIVI
	CDIP – F	Tube	CD54AC02F3A	CD54AC02F3A

<sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

# FUNCTION TABLE (each gate)

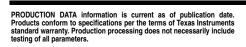
INP	JTS	OUTPUT
Α	В	Y
Н	Х	L
Х	Н	L
L	L	Н

## logic diagram (positive logic)





Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.





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## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V <sub>CC</sub>	–0.5 V to 6 V
Input clamp current, $I_{ K }(V_{ } < 0 \text{ or } V_{ } > V_{CC})$ (see Note 1)	±20 mA
Output clamp current, I <sub>OK</sub> (V <sub>O</sub> < 0 or V <sub>O</sub> > V <sub>CC</sub> ) (see Note 1)	±50 mA
Continuous output current, I <sub>O</sub> (V <sub>O</sub> = 0 to V <sub>CC</sub> )	±50 mA
Continuous current through V <sub>CC</sub> or GND	±100 mA
Package thermal impedance, $\theta_{JA}$ (see Note 2): E package	80°C/W
M package	86°C/W
Storage temperature range, T <sub>sto</sub>	_65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

## recommended operating conditions (see Note 3)

			T <sub>A</sub> = 2	25°C	–40°C 85°		–55°C 125		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
Vcc	Supply voltage		1.5	5.5	1.5	5.5	1.5	5.5	V
		V <sub>CC</sub> = 1.5 V	1.2		1.2		1.2		
۷ıн	High-level input voltage	V <sub>CC</sub> = 3 V	2.1		2.1		2.1		V
		V <sub>CC</sub> = 5.5 V	3.85		3.85		3.85		
		V <sub>CC</sub> = 1.5 V		0.3		0.3		0.3	
$V_{IL}$	Low-level input voltage	V <sub>CC</sub> = 3 V		0.9		0.9		0.9	V
		V <sub>CC</sub> = 5.5 V		1.65		1.65		1.65	
٧ <sub>I</sub>	Input voltage		0	VCC	0	VCC	0	VCC	V
٧o	Output voltage		0	VCC	0	VCC	0	VCC	V
loh	High-level output current	V <sub>CC</sub> = 4.5 V to 5.5 V		-24		-24		-24	mA
loL	Low-level output current	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		24		24		24	mA
Δt/Δν	Input transition rise or fall rate	$V_{CC} = 1.5 \text{ V to } 3 \text{ V}$		50		50		50	ns/V
ΔυΔν	input transition rise of fall fate	$V_{CC} = 3.6 \text{ V to } 5.5 \text{ V}$		20		20		20	115/ V

NOTE 3: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.



NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

<sup>2.</sup> The package thermal impedance is calculated in accordance with JESD 51-7.

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# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CO	TEST CONDITIONS		T <sub>A</sub> =	25°C	–40°C TO 85°C		–55°C 125°		UNIT		
			VCC	MIN	MAX	MIN	MAX	MIN	MAX			
			1.5 V	1.4		1.4		1.4				
		$I_{OH} = -50  \mu A$	3 V	2.9		2.9		2.9				
			4.5 V	4.4		4.4		4.4				
Voн	$V_I = V_{IH} \text{ or } V_{IL}$	$I_{OH} = -4 \text{ mA}$	3 V	2.58		2.48		2.4		V		
		$I_{OH} = -24 \text{ mA}$	4.5 V	3.94		3.8		3.7				
		$I_{OH} = -50 \text{ mA}^{\dagger}$	5.5 V					3.85				
			5.5 V			3.85						
		I <sub>OL</sub> = 50 μA	1.5 V		0.1		0.1		0.1	.1		
			I <sub>OL</sub> = 50 μA	$I_{OL} = 50 \mu A$	3 V		0.1		0.1		0.1	
			4.5 V		0.1		0.1		0.1			
VOL	$V_I = V_{IH} \text{ or } V_{IL}$	I <sub>OL</sub> = 12 mA	3 V		0.36		0.44		0.5	V		
		I <sub>OL</sub> = 24 mA	4.5 V		0.36		0.44		0.5			
		$I_{OL} = 50 \text{ mA}^{\dagger}$	5.5 V						1.65			
		$I_{OL} = 75 \text{ mA}^{\dagger}$	5.5 V				1.65					
lı	V <sub>I</sub> = V <sub>CC</sub> or GND		5.5 V		±0.1		±1		±1	μΑ		
lcc	$V_I = V_{CC}$ or GND,	IO = 0	5.5 V		4		40		80	μΑ		
Ci					10		10		10	pF		

<sup>†</sup> Test one output at a time, not exceeding 1-second duration. Measurement is made by forcing indicated current and measuring voltage to minimize power dissipation. Test verifies a minimum 50-Ω transmission-line drive capability at 85°C and 75-Ω transmission-line drive capability at 125°C.

# switching characteristics over recommended operating free-air temperature range, $V_{CC}$ = 1.5 V, $C_L$ = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	–40°C 85°		–55°C 125		UNIT
	(INFOT)	(001F01)	MIN	MAX	MIN	MAX	
<sup>t</sup> PLH	A or B	V		131		144	no
<sup>t</sup> PHL	AUID	ī		131		144	ns

# switching characteristics over recommended operating free-air temperature range, $V_{CC}$ = 3.3 V $\pm$ 0.3 V, $C_L$ = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	–40°( 85°		–55°C 125		UNIT
	(1141 01)	(001101)	MIN	MAX	MIN	MAX	
t <sub>PLH</sub>	A or B	V	4.1	14.6	4	16.1	no
t <sub>PHL</sub>	AUID	ī	4.1	14.6	4	16.1	ns

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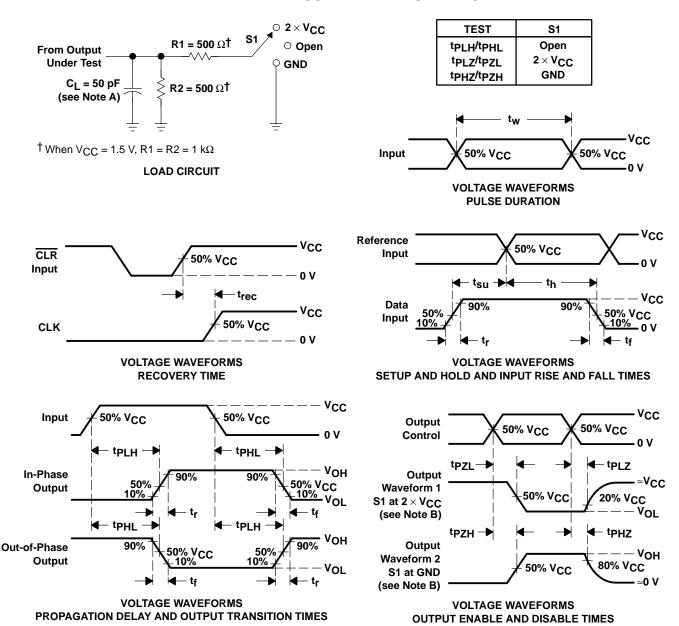
# switching characteristics over recommended operating free-air temperature range, $V_{CC}$ = 5 V $\pm$ 0.5 V, $C_L$ = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	–40°0 85°		–55°C 125	-	UNIT
	(1141 01)	(0011 01)	MIN	MAX	MIN	MAX	
t <sub>PLH</sub>	A or B	V	3	10.4	2.9	11.5	no
<sup>t</sup> PHL	AUIB	Υ	3	10.4	2.9	11.5	ns

# operating characteristics, $V_{CC}$ = 5 V, $T_A$ = 25°C

	PARAMETER	TYP	UNIT
Cr	Power dissipation capacitance	55	pF

### PARAMETER MEASUREMENT INFORMATION



NOTES: A. C<sub>L</sub> includes probe and test-fixture capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz,  $Z_O = 50 \Omega$ ,  $t_f = 3$  ns,  $t_f = 3$  ns. Phase relationships between waveforms are arbitrary.
- D. For clock inputs, f<sub>max</sub> is measured with the input duty cycle at 50%.
- E. The outputs are measured one at a time with one input transition per measurement.
- F. tpLH and tpHL are the same as tpd.
- G. tpzL and tpzH are the same as ten.
- H. tpLz and tpHz are the same as tdis.

Figure 1. Load Circuit and Voltage Waveforms



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.com 9-Oct-2007

### **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
CD54AC02F3A	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
CD74AC02E	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CD74AC02EE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CD74AC02M	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74AC02M96	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74AC02M96E4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74AC02M96G4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74AC02ME4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74AC02MG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

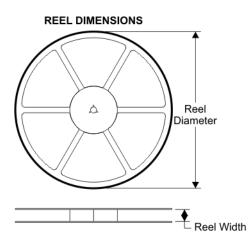
(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

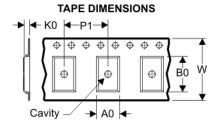
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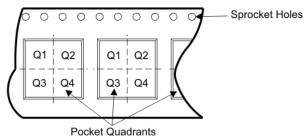
### TAPE AND REEL BOX INFORMATION





	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
	Overall width of the carrier tape
P1	Pitch between successive cavity centers

### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



Device	Package	Pins	Site	Reel Diameter (mm)	Reel Width (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD74AC02M96	D	14	SITE 41	330	16	6.5	9.0	2.1	8	16	Q1





Device	Package	Pins	Site	Length (mm)	Width (mm)	Height (mm)
CD74AC02M96	D	14	SITE 41	346.0	346.0	33.0

## 14 LEADS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

# N (R-PDIP-T\*\*)

## PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



# D (R-PDSO-G14)

# PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
- Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
- E. Reference JEDEC MS-012 variation AB.



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